



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Attorney Docket No.: **W1010.132-US-01**
[Formerly 134.136]

Hideo OSANAI, et al.

Confirmation No.: 7450

Application No.: 09/848,140

Examiner: Tuan T. DINH

Filed: May 3, 2001

Group Art Unit: 2827

For: METAL CERAMIC CIRCUIT BOARD AND MANUFACTURING METHOD
THEREOF

AMENDMENT

Box Non-Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action of October 2, 2002, amendment to the above-identified patent application is requested.

IN THE TITLE:

Please substitute the following amended title for the title as currently on record:

METAL-CERAMIC CIRCUIT BOARD

IN THE CLAIMS

Please amend claim 1 as follows:

1. (Once Amended) A metal-ceramic circuit board comprising a base plate of aluminum or aluminum alloy and a ceramic substrate board, wherein one surface of the ceramic substrate board is bonded directly to the base plate.

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